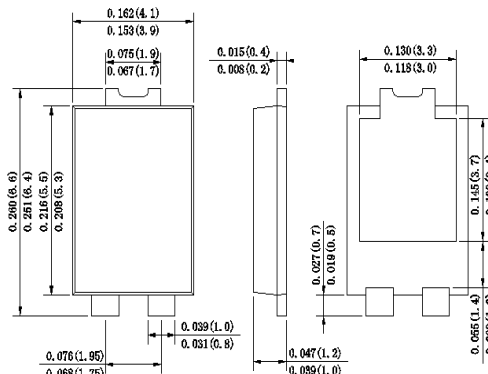


Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low forward voltage drop
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
260°C/10 seconds at terminals

TO-277B



LEFT PIN  RIGHT PIN  BOTTOMSIDE HEAT SINK 

Dimensions in inches and (millimeters)

Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.003 ounce, 0.092 grams

Maximum Ratings (Ta=25 unless otherwise specified)

PARAMETER	SYMBOLS	SBRT20U60SP5-7-CN	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	60	V
Maximum RMS voltage	V_{RMS}	42	V
Maximum DC blocking voltage	V_{DC}	60	V
Maximum average forward rectified current at $T_L=100^{\circ}C$	$I_{(AV)}$	20.0	A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	350.0	A
Typical thermal resistance	R_{qJC}	8	$^{\circ}C/W$
Operating junction temperature range	T_J	-55 to +150	$^{\circ}C$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}C$

Note: Thermal resistance from junction to case lead mounted on P.C.B. with 10.0 mm x 10.0 mm) copper pad areas

Electrical Characteristics (Ta=25 unless otherwise specified)

PARAMETER	SYMBOLS	TYPE	MAX	UNITS
Maximum instantaneous forward voltage at 20.0A	V_F	0.50	0.55	V
Maximum DC reverse current at rated DC blocking voltage	I_R	100 5	500 20	μA mA
	$T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$			

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

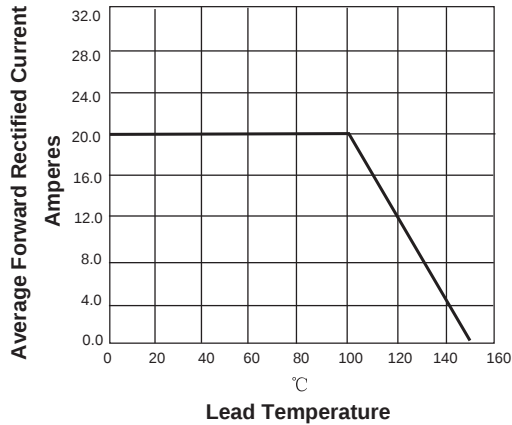


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

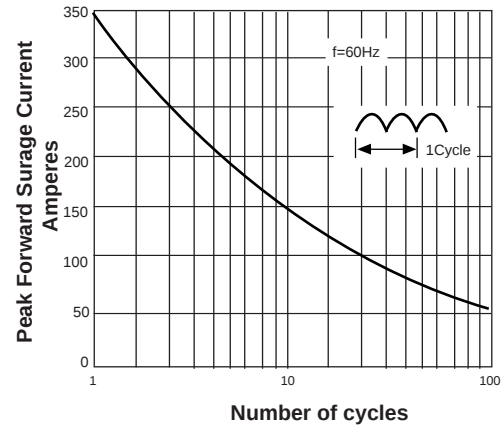


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

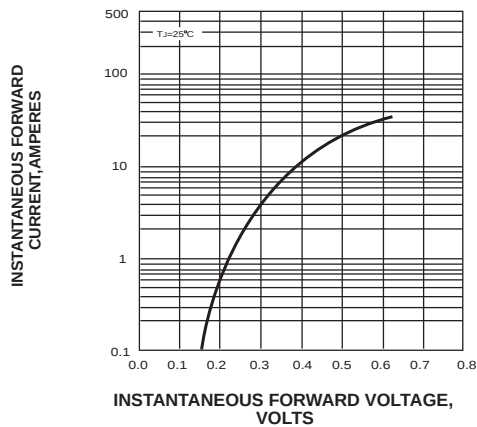
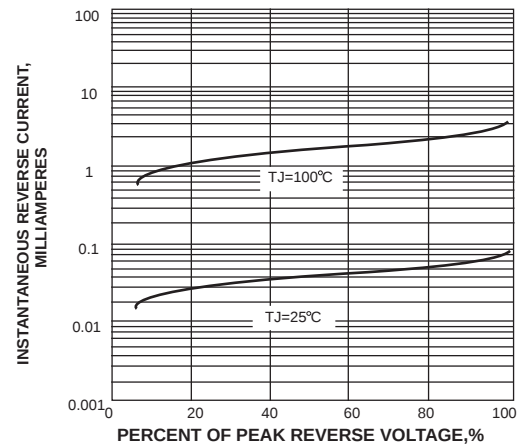
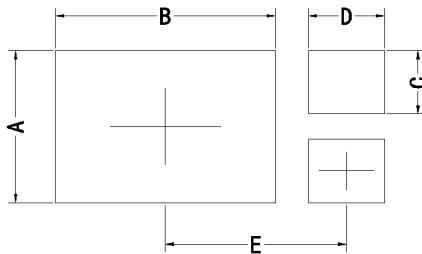


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

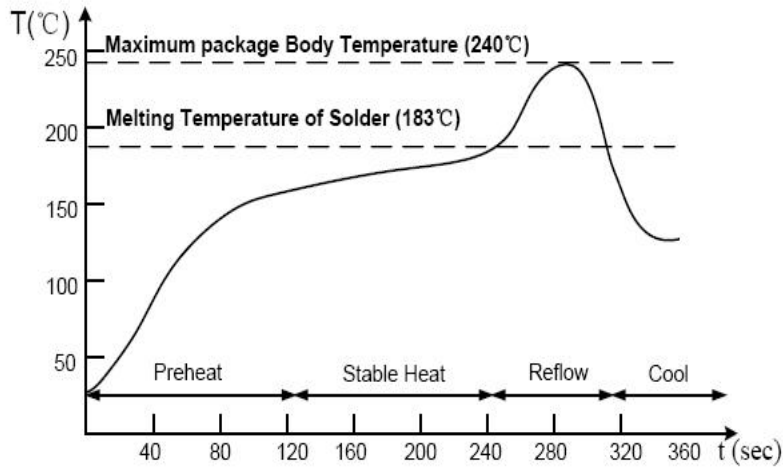


Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	3.60	0.142
B	5.35	0.211
C	1.50	0.059
D	1.85	0.073
E	4.30	0.169

Suggested Soldering Temperature Profile

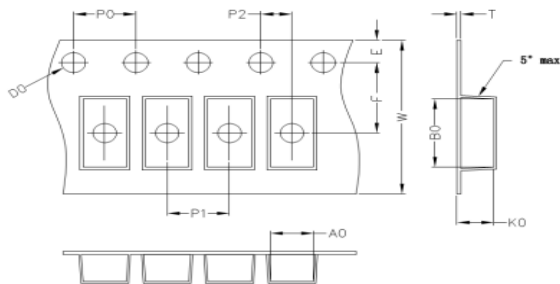


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
4.40	6.90	1.30	1.55	1.75	7.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
TO-277B	13'	330	5.0	340	10.0	360*360*360	80

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